

APPLICABLE STANDARD								
RATING	OPERATING TEMPERATURE RANGE	-30°C TO 85°C (NOTE 1)	STORAGE TEMPERATURE RANGE		-10°C TO 60°C (NOTE 3)			
	OPERATING HUMIDITY RANGE	40% TO 80% (NOTE 2)	STORAGE HUMIDITY RANGE		40% TO 70% (NOTE 3)			
	APPLICABLE CONNECTOR	MDF6-*DS-3. 5C	APPLICABLE CONTACT		MDF6-***SCF (##)			
	VOLTAGE	300V AC/DC	UL・CSA RATING	VOLTAGE	UL: 250V AC/DC CSA: 30V AC/DC			
	CURRENT	7A/pin		CURRENT	6A/pin			
SPECIFICATIONS								
ITEM		TEST METHOD		REQUIREMENTS		QT	AT	
CONSTRUCTION								
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.		X	X	
MARKING		CONFIRMED VISUALLY.				X	X	
ELECTRIC CHARACTERISTICS								
CONTACT RESISTANCE		20 mV MAX, 1mA (DC OR 1000 Hz)		30mΩ MAX.		X	—	
INSULATION RESISTANCE		500V DC.		1000MΩ MIN.		X	—	
VOLTAGE PROOF		1500V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.		X	—	
MECHANICAL CHARACTERISTICS								
MECHANICAL OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.		1) CONTACT RESISTANCE: 30mΩ MAX. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—	
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.		1) NO ELECTRICAL DISCONTINUITY OF 1μs. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—	
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		1) NO ELECTRICAL DISCONTINUITY OF 1μs. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—	
ENVIRONMENTAL CHARACTERISTICS								
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 TO 95 %, 96 h.		1) CONTACT RESISTANCE: 30mΩ MAX. 2) INSULATION RESISTANCE: 1000MΩ MIN. 3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—	
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55→ 5 TO 35→85→ 5 TO 35 °C TIME 30→ 2 TO 3→ 30→ 2 TO 3 min UNDER 5 CYCLES.		1) CONTACT RESISTANCE: 30mΩ MAX. 2) INSULATION RESISTANCE: 1000MΩ MIN. 3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—	
RESISTANCE TO SOLDERING HEAT		1) SOLDER BATH METHOD SOLDER TEMPERATURE 260 °C, FOR IMMERSION DURATION 10 s. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE 350 °C FOR 3 SEC. NO STRENGTH ON CONTACT		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.		X	—	
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE, 245±3°C FOR IMMERSION , DURATION, 5 s.		SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.		X	—	
REMARKS								
NOTE 1: INCLUDING TEMPERATURE RISE BY CURRENT								
NOTE 2: NO CONDENSING								
NOTE 3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE MOUNTED ON PCB. AFTER MOUNTED ON PCB, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.								
	COUNT	DESCRIPTION OF REVISIONS		DESIGNED		CHECKED		DATE
△								
Unless otherwise specified, refer to IEC 60512.				APPROVED	HS. OKAWA	20200313		
				CHECKED	TS. KUMAZAWA	20200313		
				DESIGNED	HK. HAYASHI	20200313		
				DRAWN	DS. HIROWATARI	20200306		
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				DRAWING NO.		ELC-162426-23-00		
HRS	SPECIFICATION SHEET			PART NO.	MDF6-*DP-3. 5DS (23)			
	HIROSE ELECTRIC CO., LTD.			CODE NO.	CL547	△	1/1	